

2017 16th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm 2017)

**Orlando, Florida, USA
30 May - 2 June 2017**

Pages 1-786



**IEEE Catalog Number: CFP17ITH-POD
ISBN: 978-1-5090-2995-2**

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IEEE Catalog Number:	CFP17ITH-POD
ISBN (Print-On-Demand):	978-1-5090-2995-2
ISBN (Online):	978-1-5090-2994-5
ISSN:	1087-9870

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